

SN74ALVCH16821

3.3-V 20-BIT BUS-INTERFACE FLIP-FLOP WITH 3-STATE OUTPUTS

SCES037 – JULY 1995

- Member of the Texas Instruments *Widebus™* Family
- *EPIC™* (Enhanced-Performance Implanted CMOS) Submicron Process
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

description

This 20-bit bus-interface flip-flop is designed for 2.3-V to 3.6-V V_{CC} operation.

The SN74ALVCH16821 can be used as two 10-bit flip-flops or one 20-bit flip-flop. The 20 flip-flops are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the device provides true data at the Q outputs.

A buffered output-enable (\overline{OE}) input can be used to place the ten outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

\overline{OE} does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16821 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN74ALVCH16821 is characterized for operation from -40°C to 85°C .

DGG OR DL PACKAGE
(TOP VIEW)

$\overline{1OE}$	1	56	1CLK
1Q1	2	55	1D1
1Q2	3	54	1D2
GND	4	53	GND
1Q3	5	52	1D3
1Q4	6	51	1D4
V_{CC}	7	50	V_{CC}
1Q5	8	49	1D5
1Q6	9	48	1D6
1Q7	10	47	1D7
GND	11	46	GND
1Q8	12	45	1D8
1Q9	13	44	1D9
1Q10	14	43	1D10
2Q1	15	42	2D1
2Q2	16	41	2D2
2Q3	17	40	2D3
GND	18	39	GND
2Q4	19	38	2D4
2Q5	20	37	2D5
2Q6	21	36	2D6
V_{CC}	22	35	V_{CC}
2Q7	23	34	2D7
2Q8	24	33	2D8
GND	25	32	GND
2Q9	26	31	2D9
2Q10	27	30	2D10
$\overline{2OE}$	28	29	2CLK



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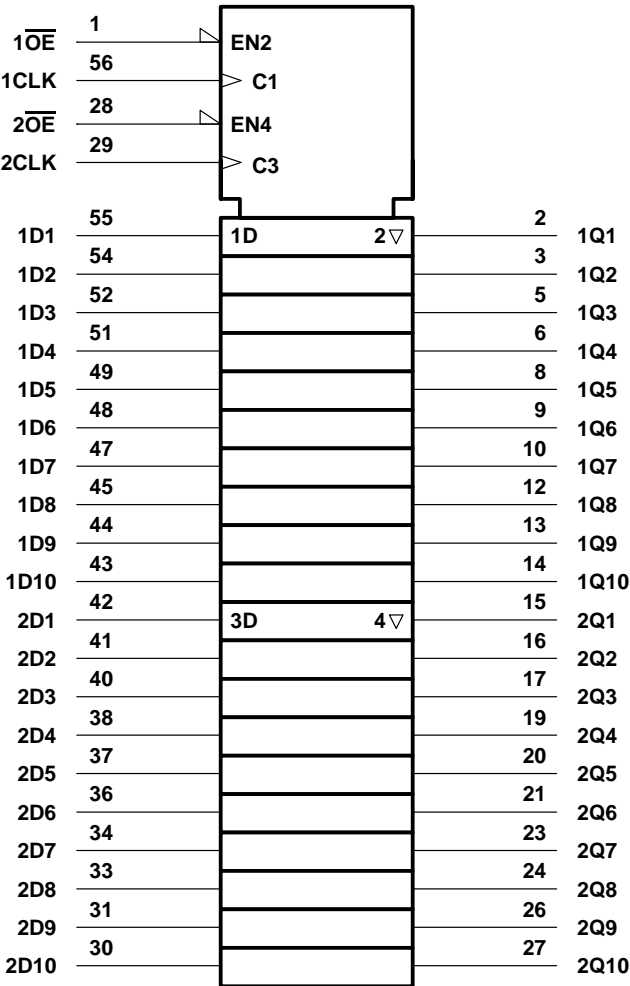
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FUNCTION TABLE

(each 10-bit flip-flop)

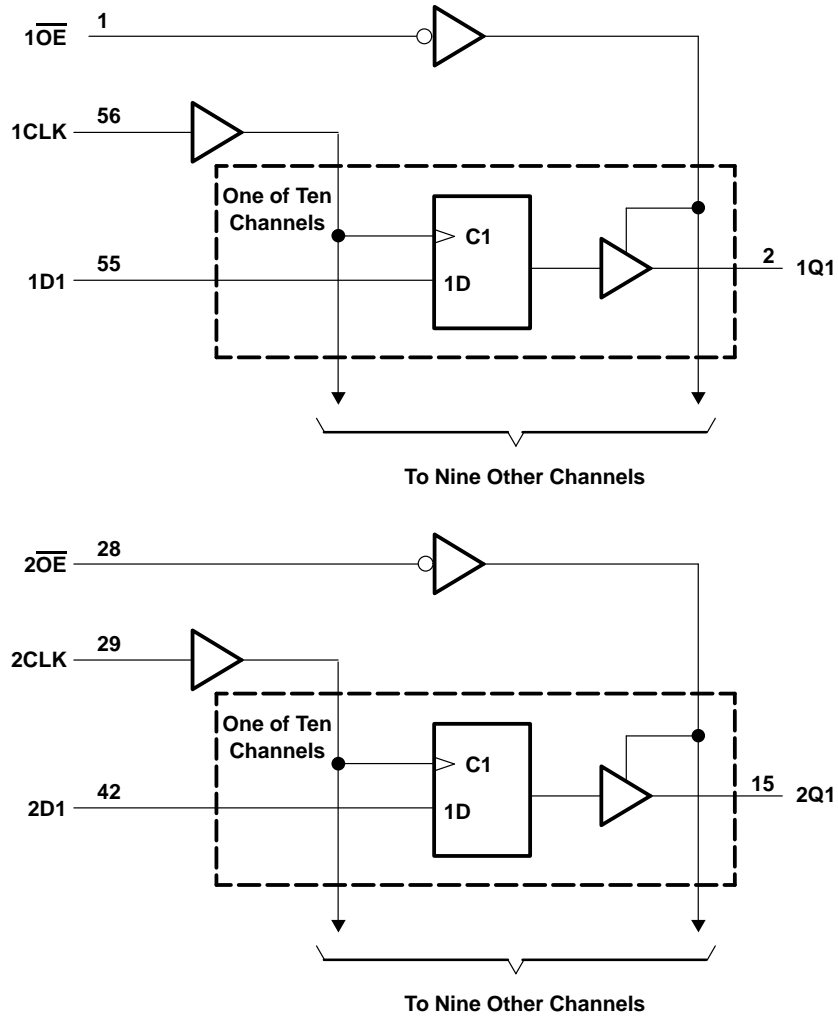
INPUTS			OUTPUT Q
\overline{OE}	CLK	D	
L	\uparrow	H	H
L	\uparrow	L	L
L	H or L	X	Q_0
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



SN74ALVCH16821

3.3-V 20-BIT BUS-INTERFACE FLIP-FLOP WITH 3-STATE OUTPUTS

SCES037 – JULY 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 4.6 V
Output voltage range, V_O (see Notes 1 and 2)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through each V_{CC} or GND	±100 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 3): DGG package	1 W
DL package	1.4 W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This value is limited to 4.6 V maximum.
3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V _{CC}	Supply voltage		2.3	3.6	V
V _{IH}	High-level input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V
		V _{CC} = 2.7 V to 3.6 V	2		
V _{IL}	Low-level input voltage	V _{CC} = 2.3 V to 2.7 V	0.7		V
		V _{CC} = 2.7 V to 3.6 V	0.8		
V _I	Input voltage		0	V _{CC}	V
V _O	Output voltage		0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 2.3 V	−12		mA
		V _{CC} = 2.7 V	−12		
		V _{CC} = 3 V	−24		
I _{OL}	Low-level output current	V _{CC} = 2.3 V	12		mA
		V _{CC} = 2.7 V	12		
		V _{CC} = 3 V	24		
Δt/Δv	Input transition rise or fall rate		0	10	ns/V
T _A	Operating free-air temperature		−40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.



SN74ALVCH16821
3.3-V 20-BIT BUS-INTERFACE FLIP-FLOP
WITH 3-STATE OUTPUTS

SCES037 – JULY 1995

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC} [†]	MIN	TYP [‡]	MAX	UNIT
V _{OH}	I _{OH} = −100 μA		MIN to MAX	V _{CC} − 0.2			V
	I _{OH} = −6 mA, V _{IH} = 1.7 V		2.3 V	2			
	I _{OH} = −12 mA	V _{IH} = 1.7 V	2.3 V	1.7			
		V _{IH} = 2 V	2.7 V	2.2			
		V _{IH} = 2 V	3 V	2.4			
	I _{OH} = −24 mA, V _{IH} = 2 V		3 V	2			
V _{OL}	I _{OL} = 100 μA		MIN to MAX			0.2	V
	I _{OL} = 6 mA, V _{IL} = 0.7 V		2.3 V			0.4	
	I _{OL} = 12 mA	V _{IL} = 0.7 V	2.3 V			0.7	
		V _{IL} = 0.8 V	2.7 V			0.4	
	I _{OL} = 24 mA, V _{IL} = 0.8 V		3 V			0.55	
I _I	V _I = V _{CC} or GND		3.6 V			±5	μA
I _I (hold)	V _I = 0.7 V		2.3 V	45			μA
	V _I = 1.7 V			−45			
	V _I = 0.8 V		3 V	75			
	V _I = 2 V			−75			
	V _I = 0 to 3.6 V		3.6 V			±500	
I _{OZ}	V _O = V _{CC} or GND		3.6 V			±10	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0		3.6 V			40	μA
ΔI _{CC}		One input at V _{CC} − 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μA
C _i	Control inputs	V _I = V _{CC} or GND	3.3 V	3.5			pF
	Data inputs			6			
C _O	Outputs	V _O = V _{CC} or GND	3.3 V	7			pF

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

[‡] All typical values are measured at V_{CC} = 3.3 V, T_A = 25°C.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	0	150	0	150	0	150	MHz
t _w	Pulse duration, CLK high or low	3.3		3.3		3.3		ns
t _{su}	Setup time, data before CLK [↑]	4.4		3.9		3.4		ns
t _h	Hold time, data after CLK [↑]	0		0		0		ns



SN74ALVCH16821
3.3-V 20-BIT BUS-INTERFACE FLIP-FLOP
WITH 3-STATE OUTPUTS

SCES037 – JULY 1995

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			150		150		150		MHz
t_{pd}	CLK	Q	1	6.4	5.3		1	4.5	ns
t_{en}	$\overline{\text{OE}}$	Q	1	7.1	6.2		1	5.1	ns
t_{dis}	$\overline{\text{OE}}$	Q	1.4	5.9	5		1	4.6	ns

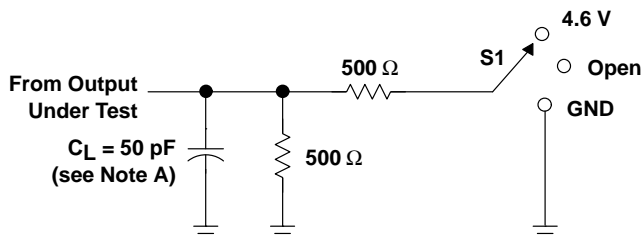
operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER			TEST CONDITIONS	$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$	$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$	UNIT
				TYP	TYP	
C_{pd} Power dissipation capacitance	Outputs enabled	$C_L = 50\text{ pF}, f = 10\text{ MHz}$		36	40	pF
	Outputs disabled			22	24	



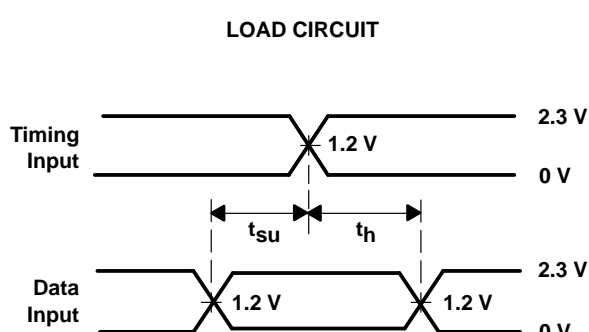
PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$$

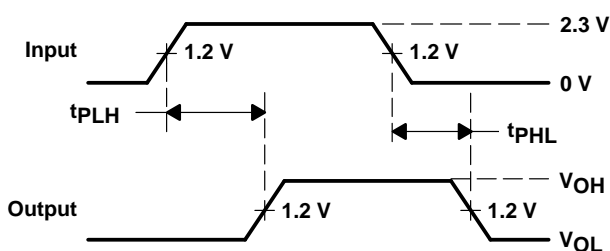


LOAD CIRCUIT

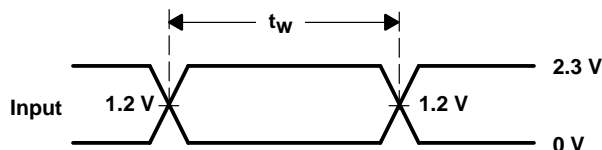
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	4.6 V
t_{PHZ}/t_{PZH}	GND



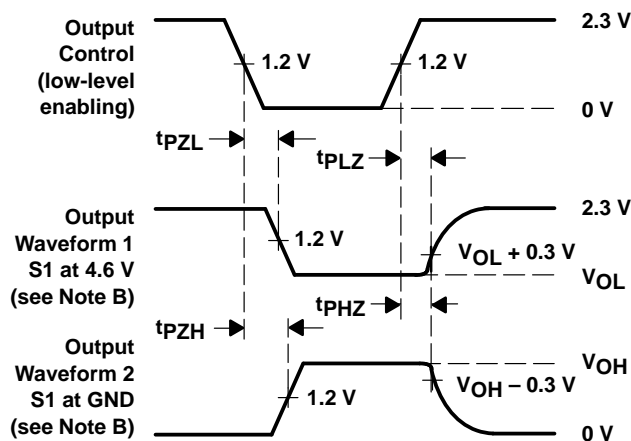
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
F. t_{PZL} and t_{PZH} are the same as t_{en} .
G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74ALVCH16821

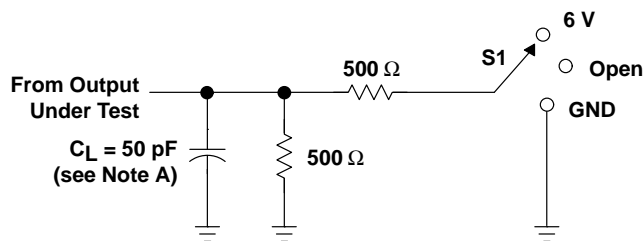
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SCES037 – JULY 1995

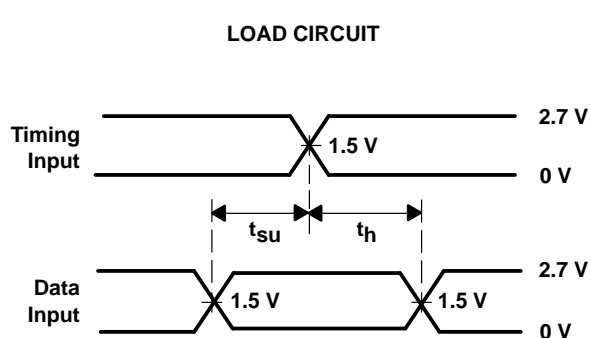
PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 2.7\text{ V AND } 3.3\text{ V} \pm 0.3\text{ V}$

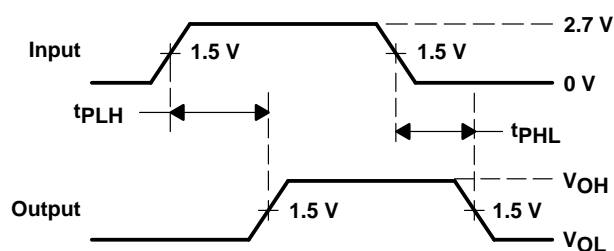


LOAD CIRCUIT

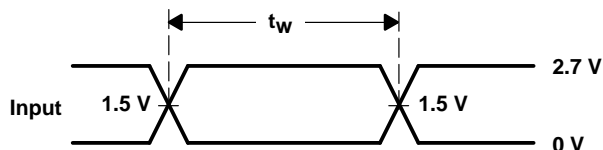
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



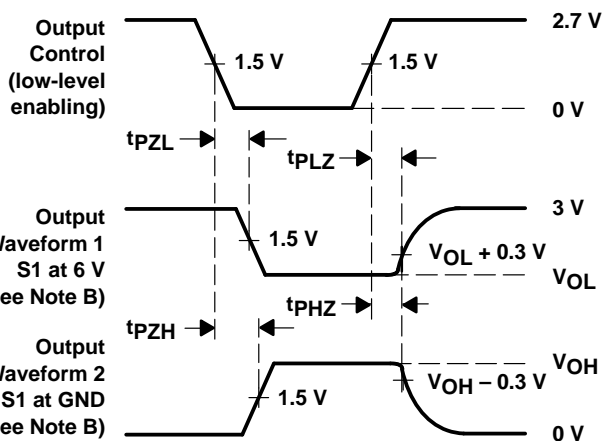
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

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